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Vibration Testing and System Dynamics is an interdisciplinary journal serving as the forum for promoting dialogues among engineering practitioners and research scholars. As the platform for facilitating the synergy of *system dynamics, testing, design, modeling, and education,* the journal publishes high-quality, original articles in the theory and applications of dynamical system testing. The aim of the journal is to stimulate more research interest in and attention for the interaction of theory, design, and application in dynamic testing. Manuscripts reporting novel methodology design for modelling and testing complex dynamical systems with nonlinearity are solicited. Papers on applying modern theory of dynamics to real-world issues in all areas of physical science and description of numerical investigation are equally encouraged. Progress made in the following topics are of interest, but not limited, to the journal:

- Vibration testing and design
- Dynamical systems and control
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- Complex system dynamics in engineering
- Dynamic failure and fatigue theory
- Chemical dynamics and bio-systems
- Fluid dynamics and combustion
- Pattern dynamics
- Network dynamics
- Control signal synchronization and tracking
- Bio-mechanical systems and devices
- Structural and multi-body dynamics
- Flow or heat-induced vibration
- Mass and energy transfer dynamics
- Wave propagation and testing
- Acoustics

No length limitations for contributions are set, but only concisely written manuscripts are published. Brief papers are published on the basis of Technical Notes. Discussions of previous published papers are welcome.

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